



DMN2400UFD

Product Summary

BV _{DSS}	RDS(ON) MAX	Ι _{D MAX} Τ _A = +25°C
	0.6Ω @ V _{GS} = 4.5V	0.9A
20V	0.8Ω @ V _{GS} = 2.5V	0.7A
200	1.0Ω @ V _{GS} = 1.8V	0.5A
	1.6Ω @ V _{GS} = 1.5V	0.3A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Load Switch

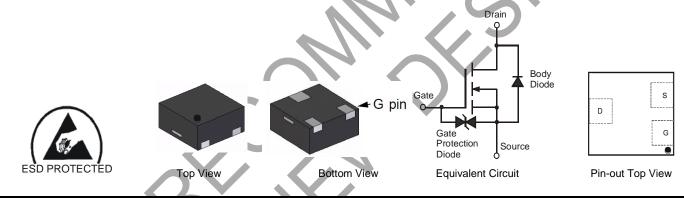
N-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

- Low On-Resistance
- Very low Gate Threshold Voltage, 1.0V Max
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1212-3
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 @4
- Terminal Connections: See Diagram
- Weight: 0.005 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2400UFD-7	X1-DFN1212-3	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information





K24 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2017) M = Month (ex: 9 = September)

Date Code K	íey
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Year	2017	20	18	2019	2020	20	21	2022	2023	20	24	2025
Code	E	F	-	G	Н		l	J	K		-	М
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				
Drain-Source Voltage				
Gate-Source Voltage				
Steady State	T _A = +25°C T _A = +70°C	ID	0.9 0.7	А
Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	0.7 0.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)				
Maximum Body Diode Forward Current (Note 6)				
	State Steady State	State $T_A = +70^{\circ}C$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$	State $T_A = +70^{\circ}C$ IDSteady $T_A = +25^{\circ}C$ IDState $T_A = +70^{\circ}C$ ID	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

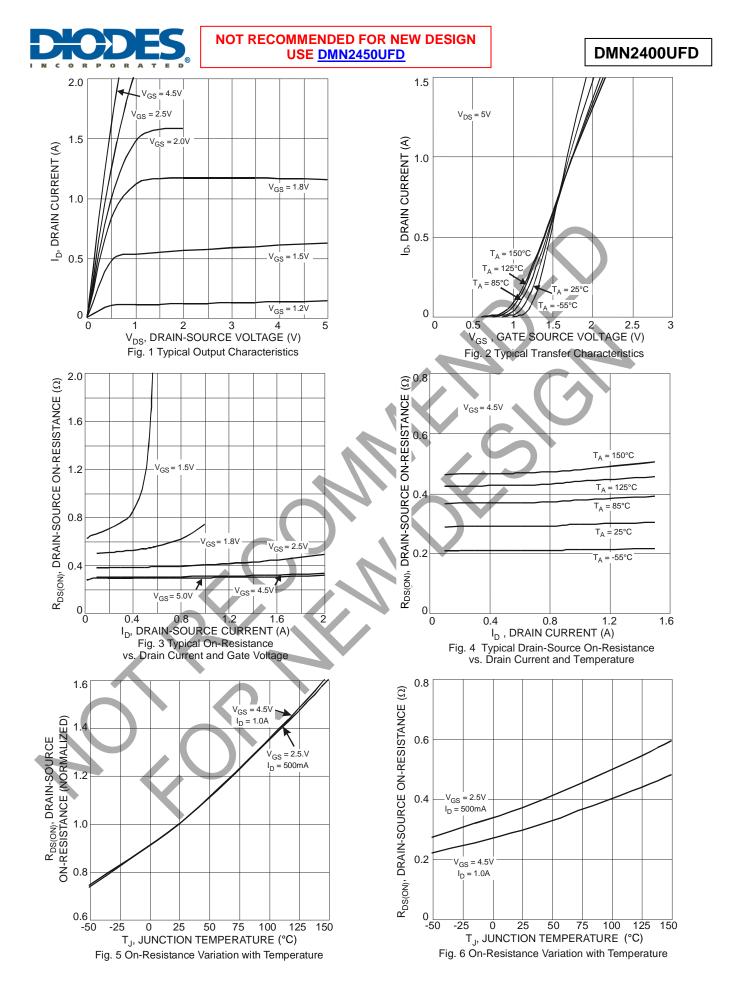
Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{0JA}	280	°C/W
Total Power Dissipation (Note 6)		PD	0.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	140	°C/W
Thermal Resistance, Junction to Case (Note 6)		R _θ Jc	112	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-		V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	-		80 100	nA	$V_{DS} = 4.5V, V_{GS} = 0V$ $V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	Igss	-	-	±1.0	μA	$V_{GS} = \pm 4.5 V, V_{DS} = 0 V$
ON CHARACTERISTICS (Note 7)						-
Gate Threshold Voltage	V _{GS(TH)}	0.45	-	1.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
		-	0.35	0.6		$V_{GS} = 4.5V, I_D = 200mA$
Static Drain-Source On-Resistance			0.45	0.8	Ω	$V_{GS} = 2.5V, I_D = 200mA$
Static Drain-Source On-Resistance	R _{DS(ON)}		0.6	1.0		$V_{GS} = 1.8V, I_D = 100mA$
		-	0.7	1.6		$V_{GS} = 1.5V, I_D = 50mA$
Forward Transfer Admittance	Y _{fs}	-	1.4	-	S	$V_{DS} = 3V, I_D = 200mA$
Diode Forward Voltage	V _{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 500mA$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	-	37.0	-	pF	
Output Capacitance	Coss	-	5.7	-	pF	V _{DS} =16V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	-	4.2	-	pF	
Gate Resistance	Rg	-	68	-	Ω	$V_{DS} = 0V, V_{GS} = 0V$
Total Gate Charge	Q _a	-	0.5	-	nC	
Gate-Source Charge	Q _{gs}	-	0.07	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q _{ad}	-	0.1	-	nC	I _D = 250mA
Turn-On Delay Time	t _{D(ON)}	-	4.06	-	ns	
Turn-On Rise Time	t _R	-	7.28	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(OFF)}	-	13.74	-	ns	R _L = 47Ω, R _g = 10Ω, I _D = 200mA
Turn-Off Fall Time	t⊢	-	10.54	-	ns	ID = 20011A

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1-inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to production testing.

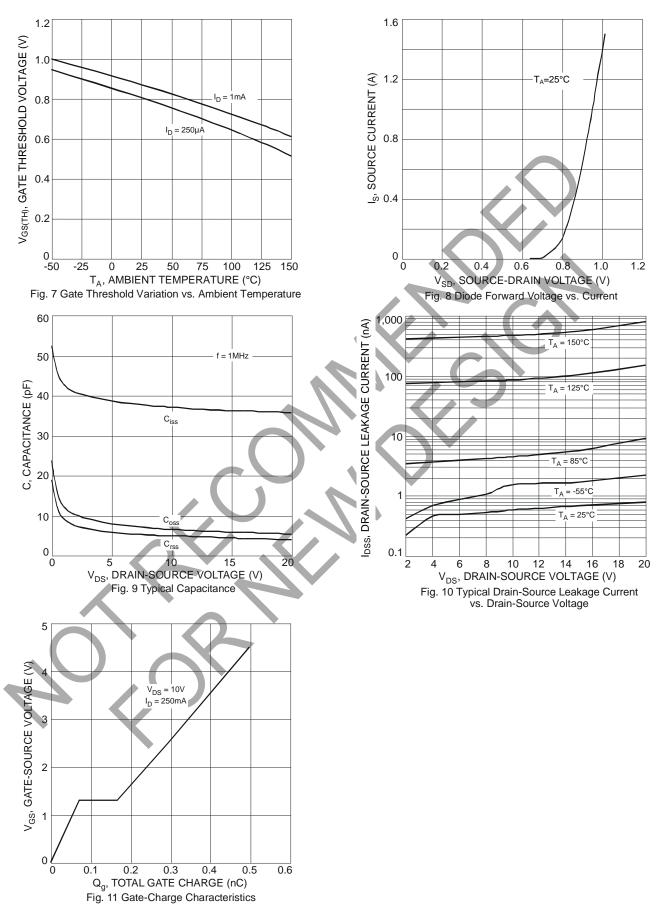
Notes:





NOT RECOMMENDED FOR NEW DESIGN USE <u>DMN2450UFD</u>

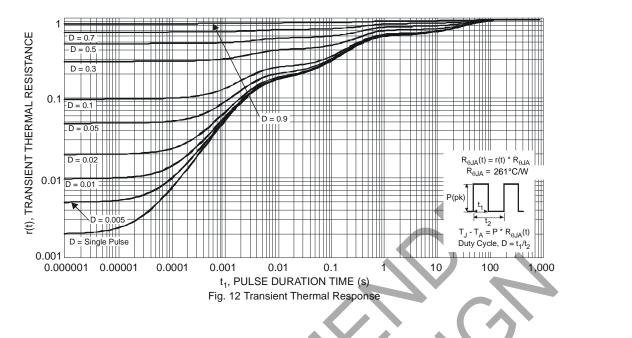
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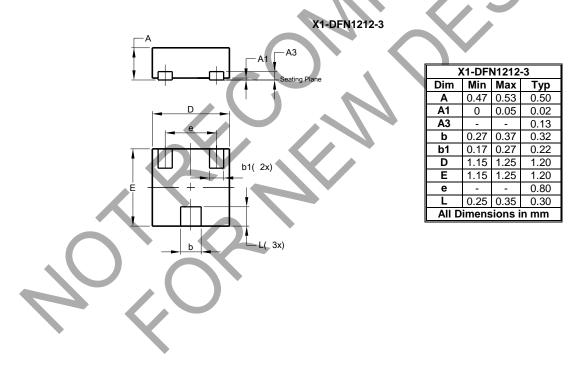
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DMN2400UFD



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.





Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1212-3



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